

HEXFET® POWER MOSFET

IRFN240 N-CHANNEL

200 Volt, 0.18Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits.

The Surface Mount Device (SMD-1) package represents another step in the continual evolution of surface mount technology. The SMD-1 will give designers the extra flexibility they need to increase circuit board density. International Rectifier has engineered the SMD-1 package to meet the specific needs of the power market by increasing the size of the termination pads, thereby enhancing thermal and electrical performance.

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D
IRFN240	200V	0.18Ω	18A

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Light-weight

Absolute Maximum Ratings


	Parameter	IRFN240	Units
I _D @ V _{GS} = 10V, T _C = 25°C	Continuous Drain Current	18	A
I _D @ V _{GS} = 10V, T _C = 100°C	Continuous Drain Current	11	
I _{DM}	Pulsed Drain Current ①	72	
P _D @ T _C = 25°C	Max. Power Dissipation	125	W
	Linear Derating Factor	1.0	W/K ⑤
V _{GS}	Gate-to-Source Voltage	±20	V
E _{AS}	Single Pulse Avalanche Energy ②	450	mJ
I _{AR}	Avalanche Current ①	18	A
E _{AR}	Repetitive Avalanche Energy ①	12.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Package Mounting Surface Temperature	300 (for 5 seconds)	
	Weight	2.6 (typical)	

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Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	200	—	—	V	$V_{GS} = 0V$, $I_D = 1.0\text{ mA}$
$\Delta BV_{DSS}/\Delta T_j$	Temperature Coefficient of Breakdown Voltage	—	0.29	—	$V/^\circ\text{C}$	Reference to 25°C , $I_D = 1.0\text{ mA}$
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.18	Ω	$V_{GS} = 10V$, $I_D = 11A$ ④
		—	—	0.25		$V_{GS} = 10V$, $I_D = 18A$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
g_{fs}	Forward Transconductance	6.1	—	—	S (④)	$V_{DS} > 15V$, $I_{DS} = 11A$ ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = 0.8 \times \text{Max Rating}$, $V_{GS} = 0V$
		—	—	250		$V_{DS} = 0.8 \times \text{Max Rating}$, $V_{GS} = 0V$, $T_j = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20V$
Q_g	Total Gate Charge	32	—	60	nC	$V_{GS} = 10V$, $I_D = 18A$ $V_{DS} = \text{Max. Rating} \times 0.5$ see figures 6 and 13
Q_{gs}	Gate-to-Source Charge	2.2	—	10.6		
Q_{gd}	Gate-to-Drain ("Miller") Charge	14.2	—	37.6		
$t_{d(on)}$	Turn-On Delay Time	—	—	20	ns	$V_{DD} = 100V$, $I_D = 18A$, $R_G = 9.1\Omega$, $V_{GS} = 10V$ see figure 10
t_r	Rise Time	—	—	152		
$t_{d(off)}$	Turn-Off Delay Time	—	—	58		
t_f	Fall Time	—	—	67		
L_D	Internal Drain Inductance	—	2.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
L_S	Internal Source Inductance	—	6.5	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
C_{iss}	Input Capacitance	—	1300	—	pF	$V_{GS} = 0V$, $V_{DS} = 25V$ $f = 1.0\text{ MHz}$ see figure 5
C_{oss}	Output Capacitance	—	400	—		
C_{rss}	Reverse Transfer Capacitance	—	130	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	18	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier. 
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	72		
V _{SD}	Diode Forward Voltage	—	—	1.5	V	T _j = 25°C, I _S = 18A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	500	ns	T _j = 25°C, I _F = 18A, di/dt ≤ 100A/μs V _{DD} ≤ 50V ④
Q _{RR}	Reverse Recovery Charge	—	—	5.3	μC	
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	1.0	K/W	
$R_{thJ-PCB}$	Junction-to-PC Board	—	TBD	—		Soldered to a copper clad PC board

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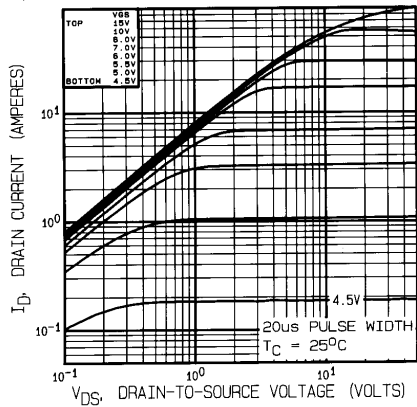


Fig. 1 — Typical Output Characteristics
 $T_C = 25^{\circ}\text{C}$

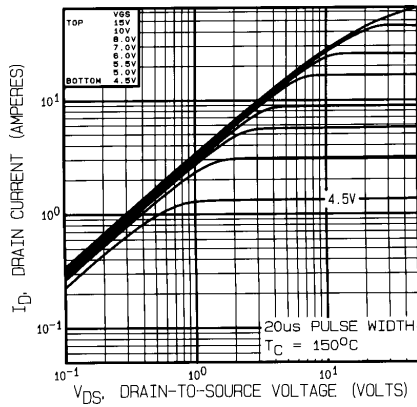


Fig. 2 — Typical Output Characteristics
 $T_C = 150^{\circ}\text{C}$

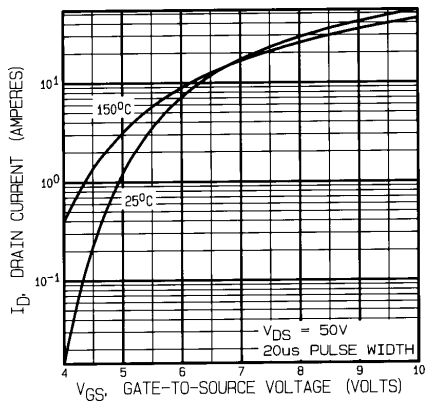


Fig. 3 — Typical Transfer Characteristics

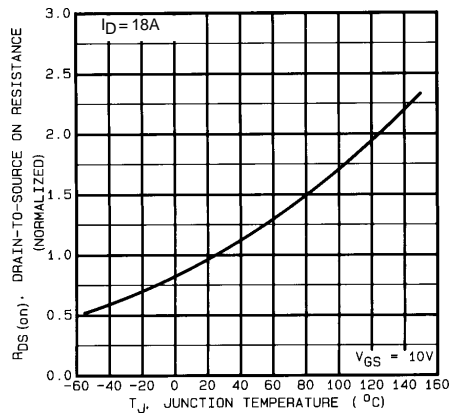


Fig. 4 — Normalized On-Resistance Vs. Temperature

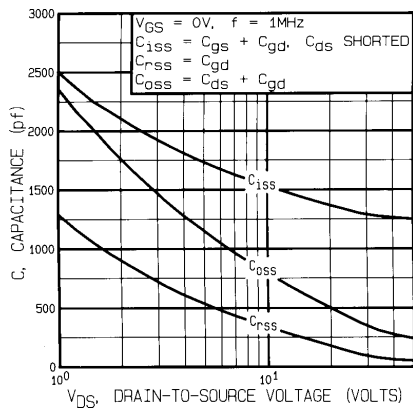


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

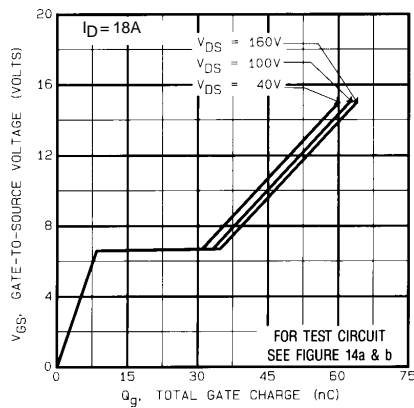


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

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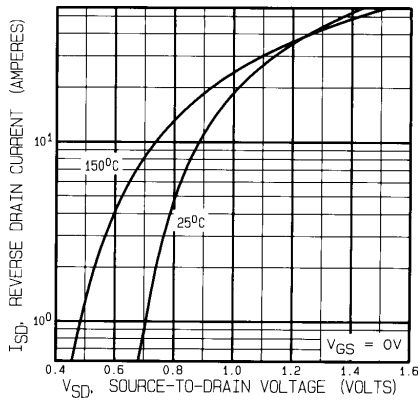


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

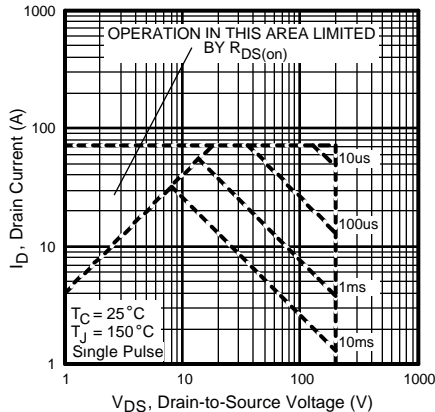


Fig. 8 — Maximum Safe Operating Area

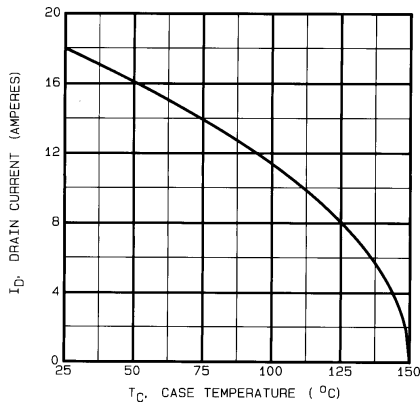


Fig. 9 — Maximum Drain Current Vs. Case Temperature

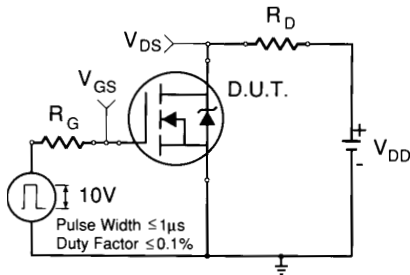


Fig. 10a — Switching Time Test Circuit

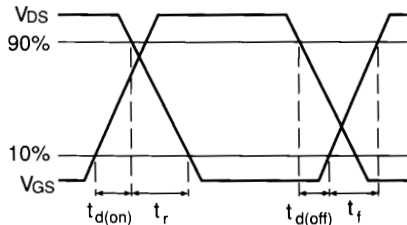


Fig. 10b — Switching Time Waveforms

IRFN240 Device

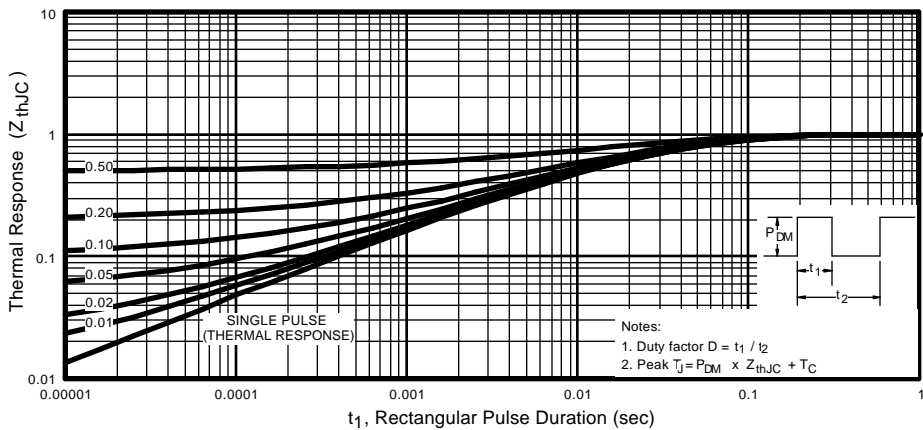


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

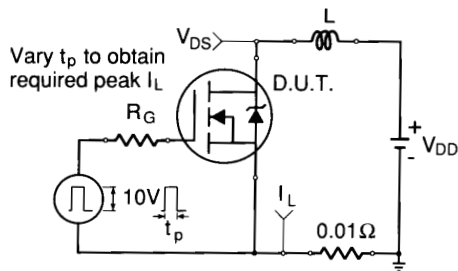


Fig. 12a — Unclamped Inductive Test Circuit

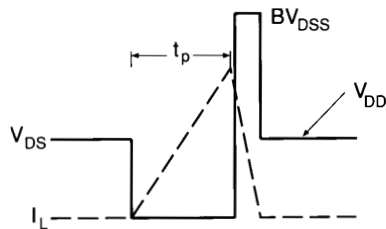


Fig. 12b — Unclamped Inductive Waveforms

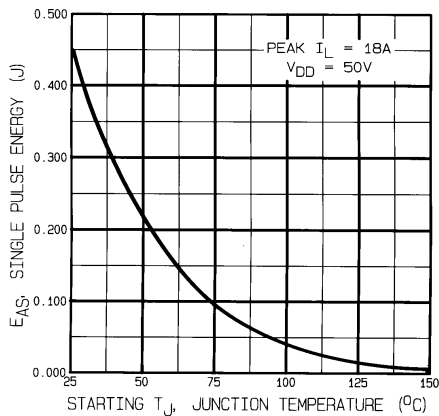


Fig. 12c — Max. Avalanche Energy vs. Current

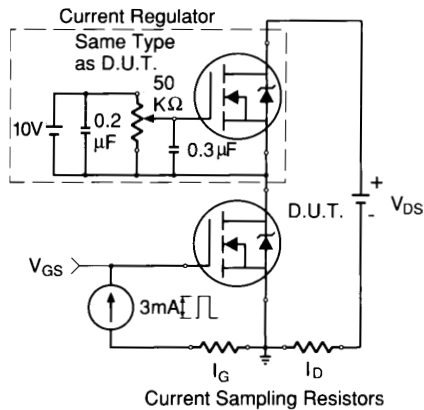


Fig. 13a — Gate Charge Test Circuit

IRFN240 Device

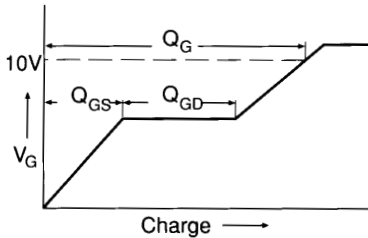
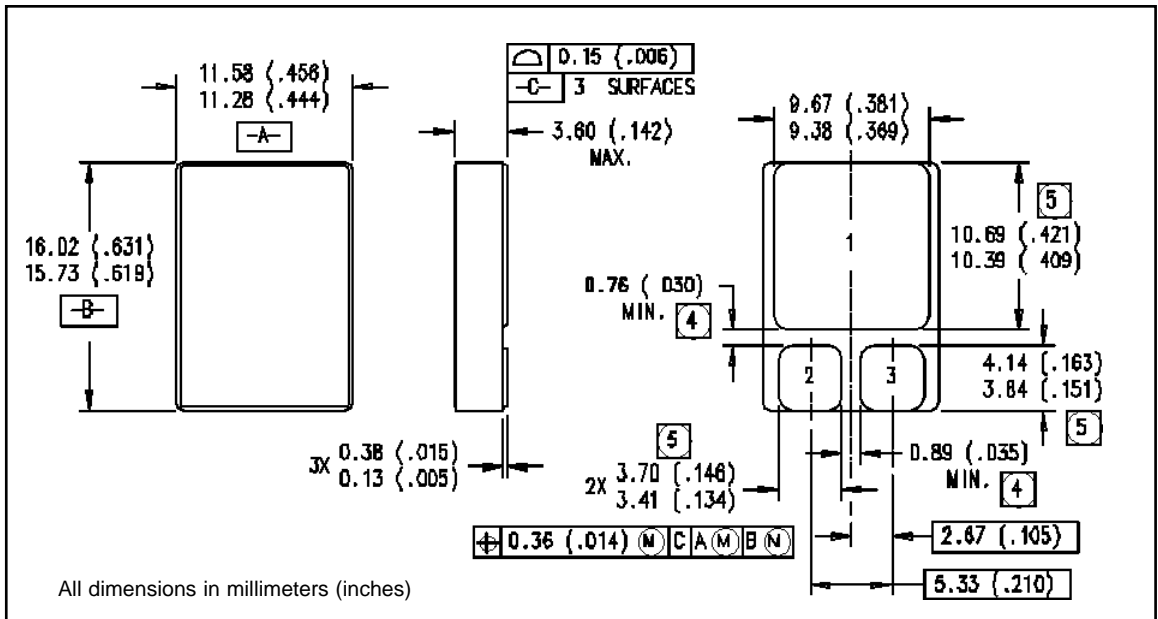


Fig. 13b — Basic Gate Charge Waveform

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
(see figure 11)
- ② @ $V_{DD} = 50V$, Starting $T_J = 25^\circ C$,
 $EAS = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS} - V_{DD})]$
Peak $I_L = 18A$, $V_{GS} = 10V$, $25 \leq R_G \leq 200\Omega$
- ③ $I_{SD} \leq 18A$, $di/dt \leq 150A/\mu s$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ $K/W = ^\circ C/W$
 $W/K = W/^\circ C$

Case Outline and Dimensions — SMD-1



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Data and specifications subject to change without notice.

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